

Certain applications or harsh environments will require additional cooling to ensure the integrity and long life of the electronics at the heart of your system. To meet these requirements HS Marston have developed the CP series of heat sinks. The large surface area and turbulence in the air flow provided by the corrugated construction ensure high levels of efficiency whether moving air is provided from an external source or from an integral fan. This construction provides a light and compact heat sink which outperforms standard extrusions of similar size.

Further improvement in performance can be obtained by attaching a fan directly to the heat sink. Fans can be attached to the heat sink using our adhesive fan gaskets making use of the latest adhesive technology which is widely used in the automotive industry. These gaskets provide a thermal barrier between the fan and the heat sink. They may also help reduce the effects of any vibration created by the fan due to bearing wear etc...

This series of heat sinks has found many applications in situations where high performance is required coupled with severe restrictions on space and height.

If you cannot satisfy your requirements from the standard range shown here, then please contact us. We will be pleased to advise you on the performance and application of sizes other than those illustrated here.

The material and flatness of the heat source are crucial factors in the selection of the correct thermally conductive adhesive tape to be used for attaching the heat sink to the chip. Please consult our sales/engineering department for assistance in choosing the correct tape before ordering.

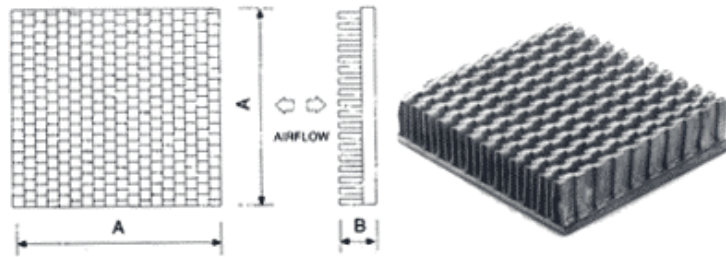


Fig. 1

Part number	A	B	PERFORMANCE °C/W	FIGURE
CP100-030-030-02-A-100	30	4.6	7	1
CP100-035-035-02-A-100	35	4.6	5.5	1
CP100-048-048-02-A-100	48	4.6	3.5	1
CP100-060-060-02-A-100	60	4.6	2.5	1
CP250-035-035-02-A-100	35	8.5	4	1
CP250-048-048-02-A-100	48	8.5	3	1
CP250-060-060-02-A-100	60	8.5	1.9	1
CP464-048-048-02-A-100	48	14	2.1	1
CP464-060-060-02-A-100	60	14	1.1	1

Performance based on 3 m/s airflow

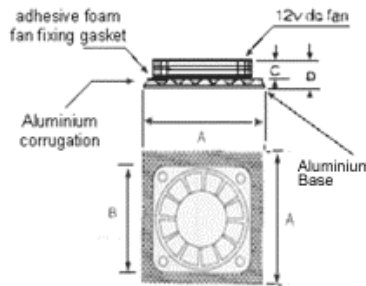
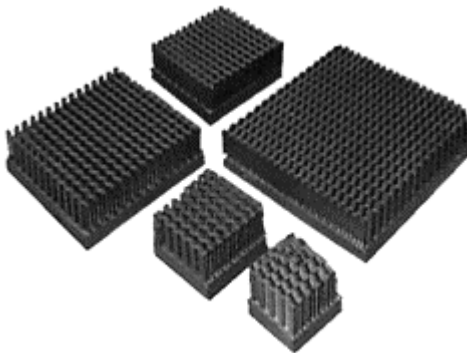
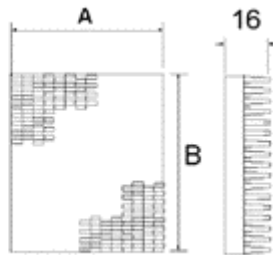
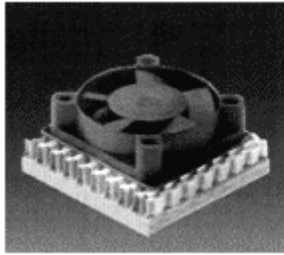


Fig. 2

Part number		A	B	C	D	PERFORMANCE °C/W	Figure
CP100-030-030-02-S-100	With fan	30	25	10	16	5	2
CP100-035-035-02-S-100	With fan	35	25	10	16	3.9	2
CP100-048-048-02-S-100	With fan	48	40	10	16	1.9	2
CP100-060-060-02-S-100	With fan	60	60	10	16	1.8	2
CP250-035-035-02-S-100	With fan	35	25	10	20	3	2
CP250-048-048-02-S-100	With fan	48	40	10	20	1.3	2
CP250-060-060-02-S-100	With fan	60	60	10	20	1.1	2
CP464-048-048-02-S-100	With fan	48	40	10	25	1.2	2
CP464-060-060-02-S-100	With fan	60	60	10	25	0.7	2

Performance based on 25mm, 40mm and 60mm fans mounted on the heat sink as shown.



Catalog number	A	B	Rth	Fan size
CP464-030-030-04-S-2	30	30	2,0° C/W	25mm square
CP464-045-045-04-S-2	45	45	1,6° C/W	40mm square
CP464-060-060-04-S-2	60	60	0,7° C/W	60mm square
CP464-080-080-04-S-2	80	80	0,4° C/W	80mm square
CP464-100-100-04-S-2	100	100	0,3° C/W	80mm square

- High performance lightweight corrugated technology.
- Sizes available to suit most devices.
- The base is machined for flatness to ensure optimum surface contact and efficiency.
- Self adhesive fan gaskets are available on request
- Base can be drilled and tapped to customer specification or device can be attached by double sided thermal tape.
- Fans are normally supplied separately.
- Custom design service is available for non standard applications.

*Self adhesive foam gaskets are available for attaching fans to the heatsinks. Prices available on request

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